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To the Honorable Commissioner of Patents and Trademarks. Please record the attached original documents or copy thereof.

1. Name of Conveying Party(ies):

(1) Masao SHINOZAKI
(2) Kenji NISHIMOTO
(3) Takashi AKIOKA
(4) Yutaka KOHARA
(5) Sanae ASARI
(6) Shusaku MIYATA
(7) Shinji NAKAZATO

Additional names of conveying parties attached: ☐ Yes ☒ No

3. Nature of Conveyance:

☒ Assignment ☐ Merger
☐ Security Agreement ☐ Change of Name
☐ Other:

Execution Dates: (1)(2)(6) February 27, 2003 (3)
February 25, 2003 (4) March 9, 2003 (5) March 17,
2003 (7) February 28, 2003

4. (a) Patent Application Number(s):

If this document is being filed together with a new application,
the execution date of the application is:

☐ Additional Numbers Attached.

2. Name and Address of Receiving Party(ies):

Name: Hitachi, Ltd.
Address: 6-6, Marunouchi 1-chome, Chiyoda-ku
City: Tokyo
Japan

and

Name: Hitachi ULSI Systems Co., Ltd.
Address: 22-1, Josuihoncho 5-chome, Kodaira-shi
City: Tokyo,
Japan

4. (b) Patent Numbers:

5. Name and Address of Party to whom Correspondence
Concerning this Document Should be Mailed:

Name: Juan Carlos A. Marquez

Address: Reed Smith LLP
3110 Fairview Park Dr.
Suite 1400
Falls Church, VA. 22042

6. Total Number of Applications and Patents Involved:

7. Total Fee: \$40.00
(37 C.F.R. § 3.41)

☒ Enclosed.
☒ Authorized to be charged to deposit account.

8. Deposit Account Number: 08-1480

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9. Statement and Signature:

To the best of my knowledge and belief, the foregoing is true and correct and any attached copy is a true copy of the
original document.

Juan Carlos A. Marquez, Registration No. 34,072

Total number of pages comprising cover sheet: 1

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ASSIGNMENT
(譲渡証)

As a below named inventor, I hereby declare that

IN CONSIDERATION of the sum of One Dollar (\$1.00) or the equivalent thereof, and other good and valuable consideration paid to me citizen of Japan by Hitachi, Ltd., and Hitachi ULSI Systems Co., Ltd., corporations organized under the laws of Japan, located at 6, Kanda Surugadai 4-chome, Chiyoda-ku, Tokyo, Japan, and 22-1, Josuihoncho 5-chome, Kodaira-shi, Tokyo, Japan, receipt of which is hereby acknowledged I do hereby sell and assign to said Hitachi, Ltd., and Hitachi ULSI Systems Co., Ltd., their successors and assigns, all my right, title and interest, in and for the United States of America, in and to

SEMICONDUCTOR INTEGRATED CIRCUIT DEVICE

invented by me (if only one is named below) or us (if plural inventors are named below) and described in the application for United States Letters Patent therefor, executed on even date herewith, and all United States Letters Patent which may be granted therefor, and all divisions, continuations and extensions thereof, the said interest being the entire ownership of the said Letters Patent when granted, to be held and enjoyed by said Hitachi, Ltd., and Hitachi ULSI Systems Co., Ltd., their successors, assigns or other legal representatives, to the full end of term for which said Letters Patent may be granted as fully and entirely as the same would have been held and enjoyed by me or us if this assignment and sale had not been made;

And I hereby agree to sign and execute any further documents or instruments which may be necessary, lawful, and proper in the prosecution of the above-named application or in the preparation and prosecution of any continuing, continuation-in-part, substitute, divisional, renewal, reviewed or reissue applications or in any amendment, extension, or interference proceedings, or otherwise to secure the title thereto in said assignee;

And I do hereby authorize and request the Commissioner of Patents to issue said Letters Patent to said Hitachi, Ltd., and Hitachi ULSI Systems Co., Ltd.,

Signed on the date(s) indicated aside our signatures:

INVENTOR(S)
(発明者フルネームサイン)

Date Signed
(署名日)

1) Masao Shinozaki Masao SHINOZAKI

27 / February / 2003

2) Kenji Nishimoto Kenji NISHIMOTO

27 / February / 2003

3) Takashi Akioka Takashi AKIOKA

25 / February / 2003

4) Yutaka Kohara Yutaka KOHARA

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5) Sanae Asari Sanae ASARI

17 / March / 2003

6) Shusaku Miyata Shusaku MIYATA

27 / February / 2003

7) Shinji Nakazato Shinji NAKAZATO

28 / February / 2003

8) _____

9) _____

10) _____

PATENT

RECORDED: 05/08/2009

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